

Applicant : Sorg et al  
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Page : 2 of 16

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Amendments to the Specification:

Please replace the paragraph [0054] with the following amended paragraph:

In order to produce a light-emitting diode component which radiates mixed colored light, the chip encapsulation may have added to it a luminescent material which absorbs at least part of the electromagnetic radiation emitted by the light-emitting diode [[5]] chip and emits electromagnetic radiation of a different wavelength and color than the absorbed radiation.

Please replace the title with the following amended title:

FABRICATING SURFACE MOUNTABLE SEMICONDUCTOR COMPONENTS  
WITH LEADFRAME STRIPS

~~ELECTRICAL LEADFRAMES, SURFACE MOUNTABLE SEMICONDUCTOR  
COMPONENTS, LEADFRAME STRIPS, AND THEIR METHOD OF MANUFACTURE~~